

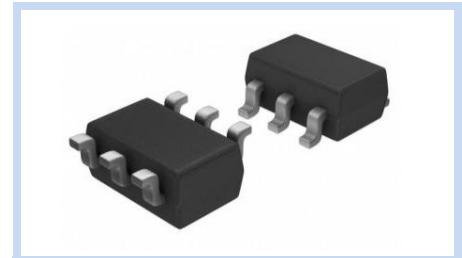
N/P Channel MOSFET
±30V 4.4A SOT-23-6 AEC-Q101

MFT3NP4A4S236A

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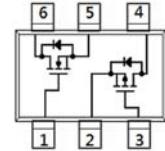
FEATURE

- $R_{DS(ON)} < 48m\Omega$, $V_{GS} = 10V$, $I_D = 4.4A$
- $R_{DS(ON)} < 70m\Omega$, $V_{GS} = 4.5V$, $I_D = 2.8A$
- Advanced Trench Process Technology
- Application: Switch Load, PWM Application, etc.
- AEC-Q101 Qualified



MECHANICAL DATA

- Case: SOT-23-6L, Molded Plastic
- Terminals: Solderable per MIL-STD-750, Method 2026

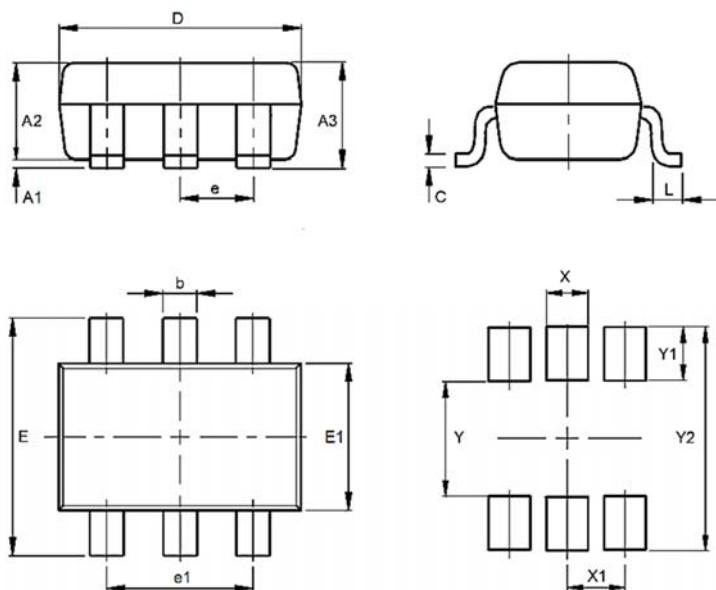


MAXIMUM RATINGS

Parameter		Symbol	Value		Unit
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	± 20	± 20	V
Drain Current – Continuous		I_D	4.4	-2.9	A
Drain Current – Pulsed		I_{DM}	17.6	-11.6	A
Power Dissipation	$T_A = 25^\circ C$	P_D	1.25		W
	Derate above $25^\circ C$		10		mW/ $^\circ C$
Thermal Resistance Junction to Ambient		$R_{\theta JA}$	100		$^\circ C/W$
Operating Junction and Storage Temperature		T_J, T_{STG}	-55 to 150		$^\circ C$

DIMENSIONS

Item	Min (mm)	Max (mm)
A1	--	0.10
A2	1.00	1.20
A3	1.00	1.30
b	0.30	0.50
c	0.08	0.20
D	2.70	3.10
E	2.60	3.00
E1	1.50	1.70
e	0.95	
e1	1.70	2.10
L	0.20	0.60
X	0.80	
X1	0.95	
Y	1.10	
Y1	0.90	
Y2	2.90	



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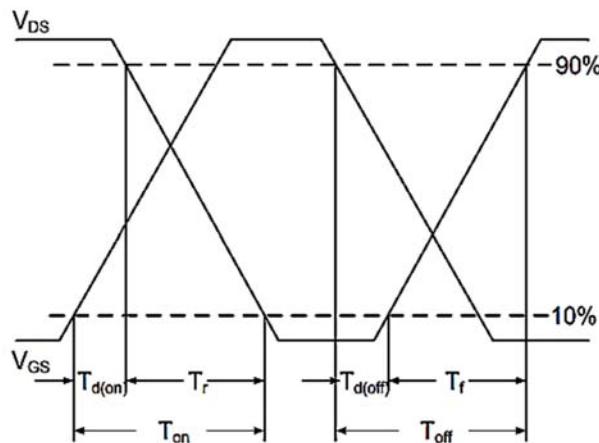
ELECTRICAL CHARACTERISTICS -N-CH

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	BV_{DSS}	30	--	--	V
Drain-Source Leakage Current	$V_{DS}=30V$, $V_{GS}=0V$,	I_{DSS}	--	--	1	μA
Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	I_{GSS}	--	--	± 100	nA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}=10V$, $I_D=4.4A$	$R_{DS(ON)}$	--	36	48	$m\Omega$
	$V_{GS}=4.5V$, $I_D=2.8A$		--	52	70	$m\Omega$
Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	$V_{GS(th)}$	1.0	1.37	2.1	V
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{DS}=15V$, $V_{GS}=10V$, $I_D=4.4A$	Q_g	--	5.8	--	nC
Gate-Source Charge		Q_{gs}	--	1	--	
Gate-Drain Charge		Q_{gd}	--	1	--	
Turn-On Delay Time	$V_{DD}=15V$, $V_{GS}=10V$, $R_G=6\Omega$ $I_D=4.4A$	$T_{d(on)}$	--	3	--	ns
Rise Time		T_r	--	39	--	
Turn-Off Delay Time		$T_{d(off)}$	--	23	--	
Fall Time		T_f	--	28	--	
Input Capacitance	$V_{DS}=15V$, $V_{GS}=0V$, $F=1MHz$	C_{iss}	--	235	--	pF
Output Capacitance		C_{oss}	--	36	--	
Reverse Transfer Capacitance		C_{rss}	--	24	--	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Continuous Source Current	$V_G=V_D=0V$, Force Current	I_s	--	--	1.5	A
Diode Forward Voltage	$V_{GS}=0V$, $I_s=1A$, $T_J=25^\circ C$	V_{SD}	--	0.8	1.2	V

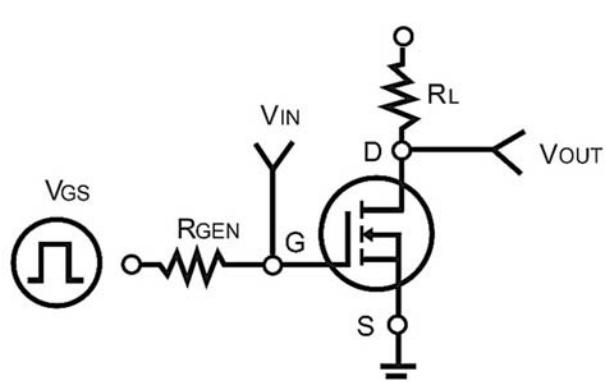
Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.
4. $T_J=25^\circ C$, unless otherwise noted.

Switching Time Waveform



Switching Test Circuit



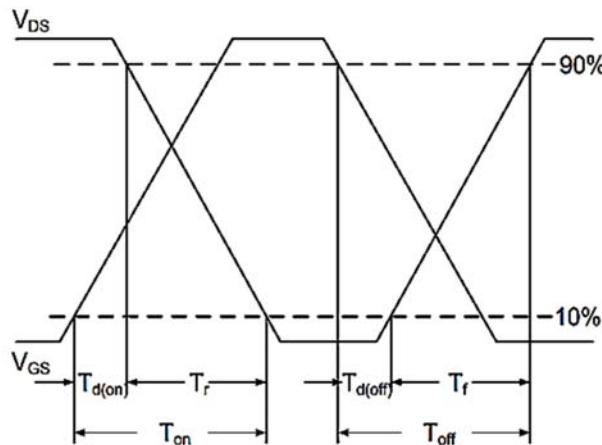
ELECTRICAL CHARACTERISTICS -P-CH

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	BV_{DSS}	-30	--	--	V
Drain-Source Leakage Current	$V_{DS}=-30V$, $V_{GS}=0V$	I_{DSS}	--	--	-1	μA
Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	I_{GSS}	--	--	± 100	nA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}=-10V$, $I_D=-2.9A$	$R_{DS(ON)}$	--	94	110	$m\Omega$
	$V_{GS}=-4.5V$, $I_D=-1.9A$		--	120	150	$m\Omega$
Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	$V_{GS(th)}$	-1	-1.3	-2.1	V
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{DS}=-15V$, $V_{GS}=-10V$, $I_D=-2.9A$	Q_g	--	9.8	--	nC
Gate-Source Charge		Q_{gs}	--	1.5	--	
Gate-Drain Charge		Q_{gd}	--	2.2	--	
Turn-On Delay Time	$V_{DD}=-15V$, $V_{GS}=-10V$, $R_G=6\Omega$ $I_D=-2.9A$	$T_{d(on)}$	--	5	--	ns
Rise Time		T_r	--	30	--	
Turn-Off Delay Time		$T_{d(off)}$	--	25	--	
Fall Time		T_f	--	8	--	
Input Capacitance	$V_{DS}=-15V$, $V_{GS}=0V$, $F=1MHz$	C_{iss}	--	396	--	pF
Output Capacitance		C_{oss}	--	47	--	
Reverse Transfer Capacitance		C_{rss}	--	36	--	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Continuous Source Current	$V_G=V_D=0V$, Force Current	I_s	--	--	-1.5	A
Diode Forward Voltage	$V_{GS}=0V$, $I_s=-1A$	V_{SD}	--	-0.85	-1.2	V

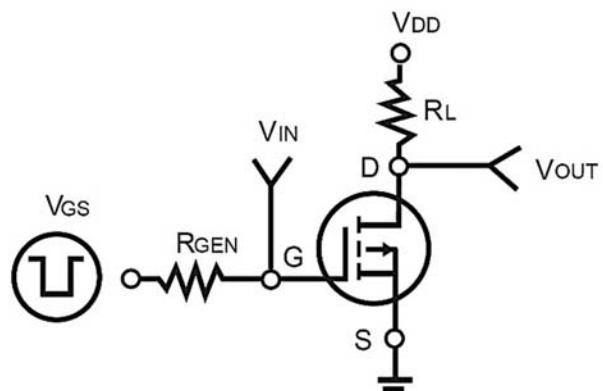
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Switching Time Waveform



Switching Test Circuit

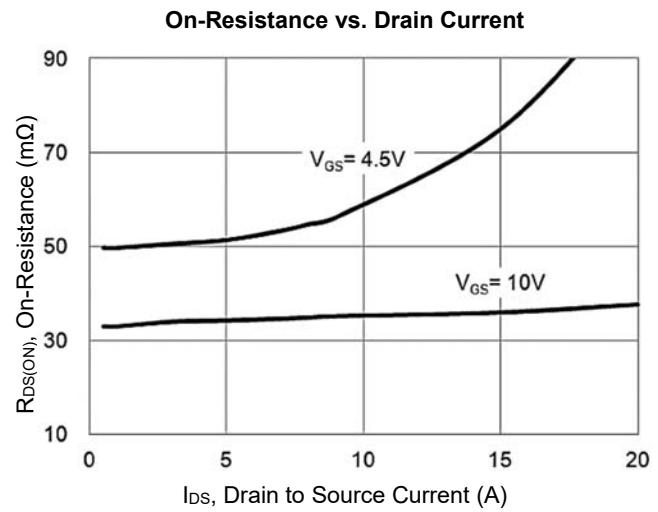
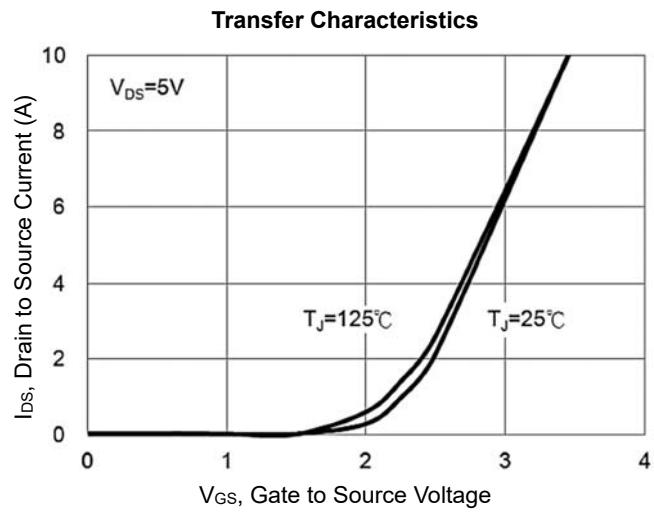
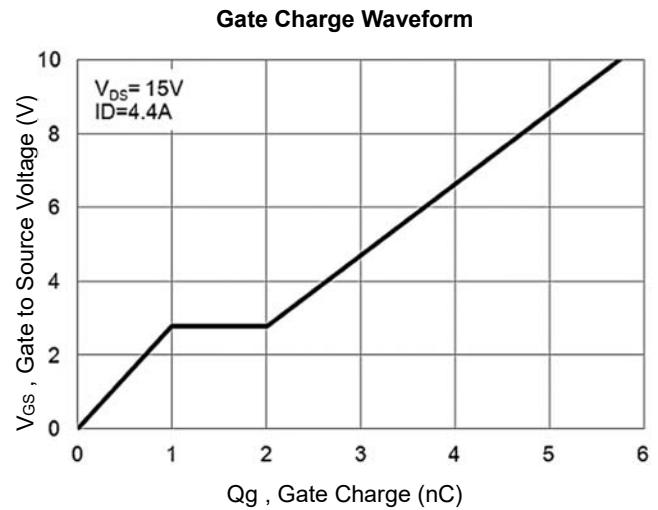
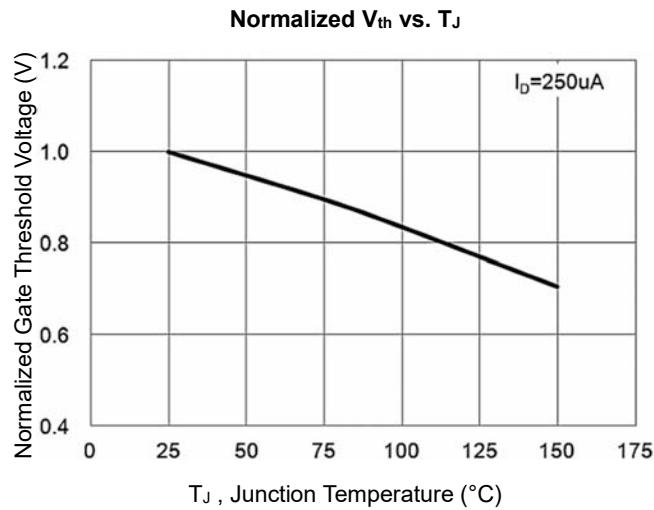
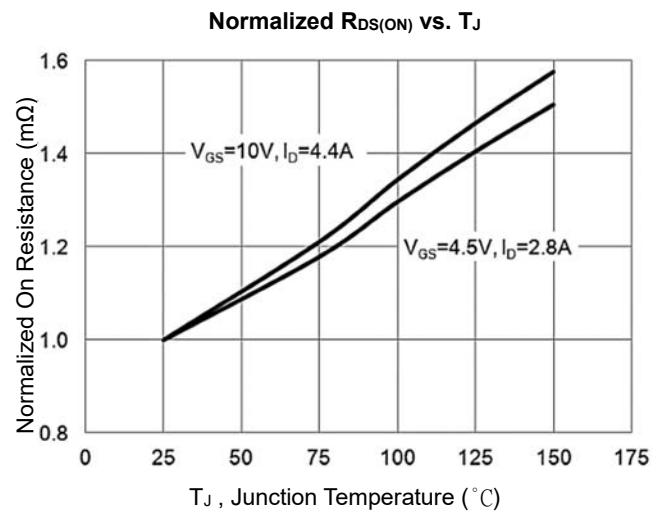
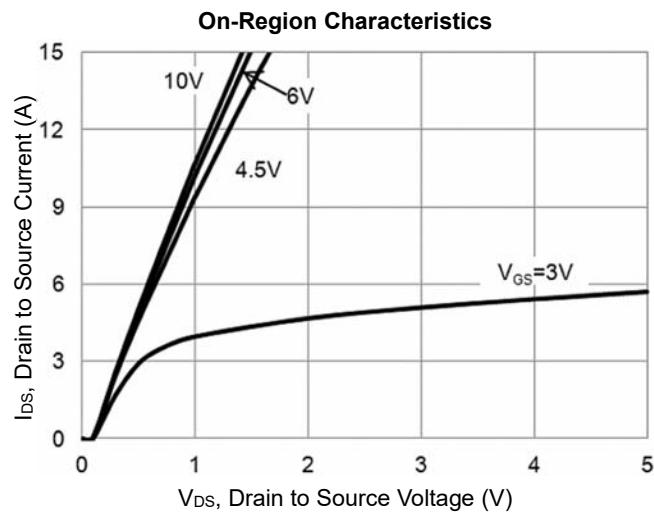


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N-CH CHARACTERISTIC CURVES



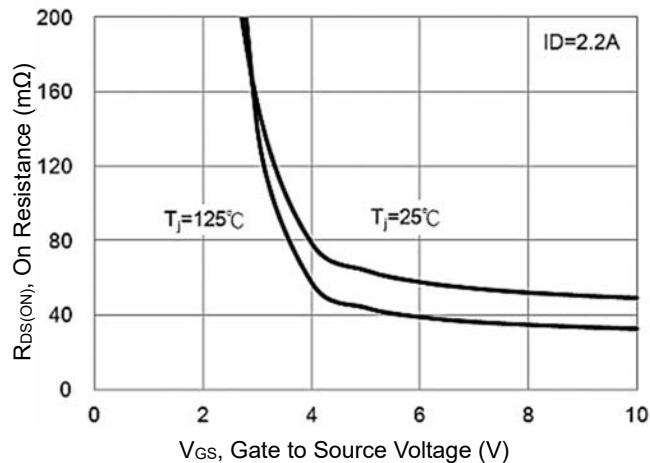
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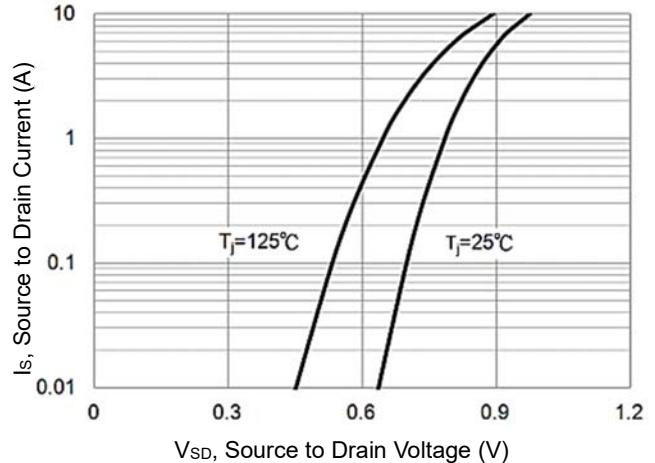
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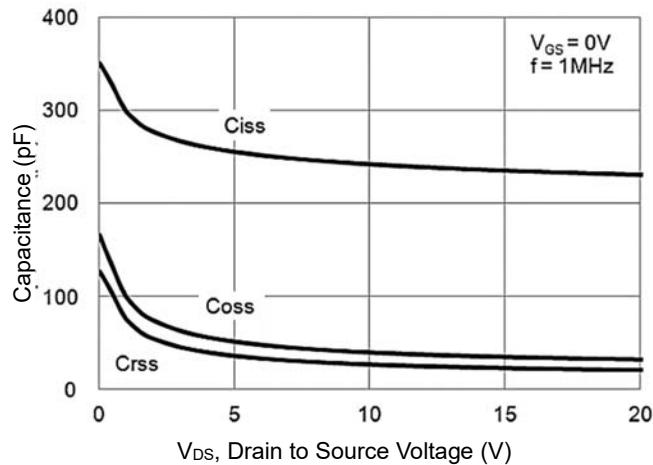
On-Resistance Variation with VGS



Body Diode



Capacitance vs. Drain-Source Voltage



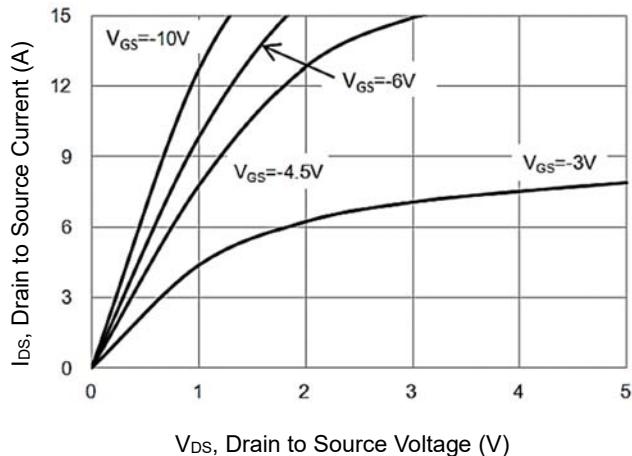
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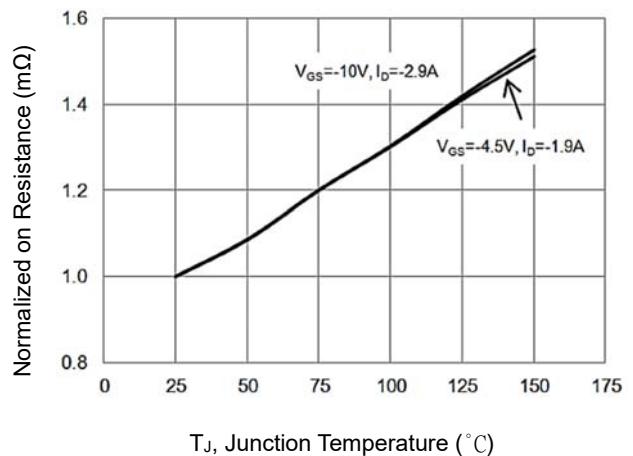
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P-CH CHARACTERISTIC CURVES

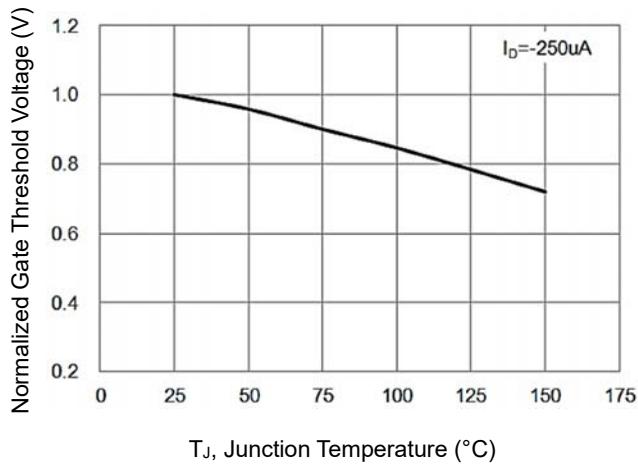
On-Region Characteristics



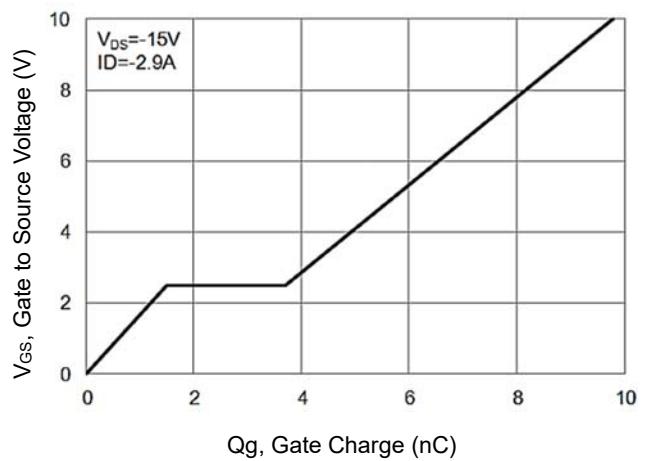
Normalized $R_{DS(ON)}$ vs. T_J



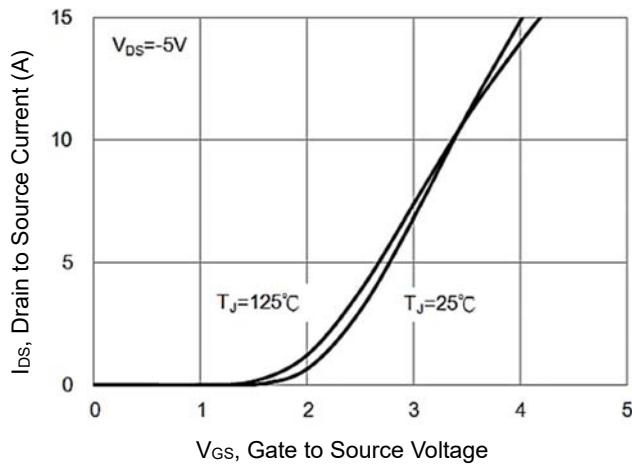
Normalized V_{th} vs. T_J



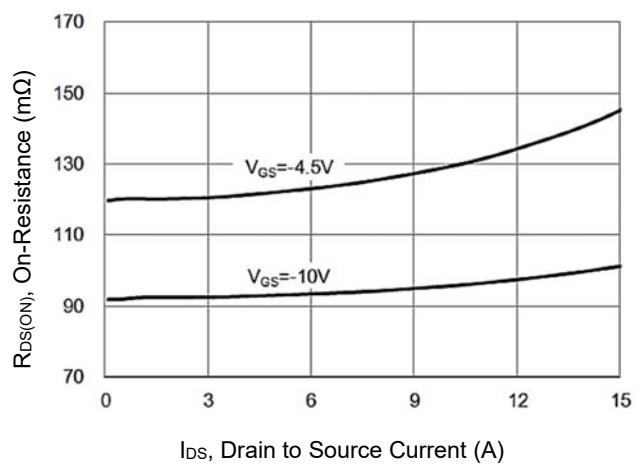
Gate Charge Waveform



Transfer Characteristics



On-Resistance vs. Drain Current



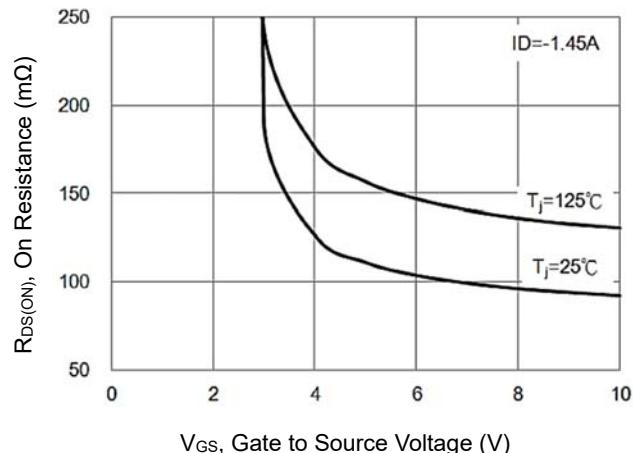
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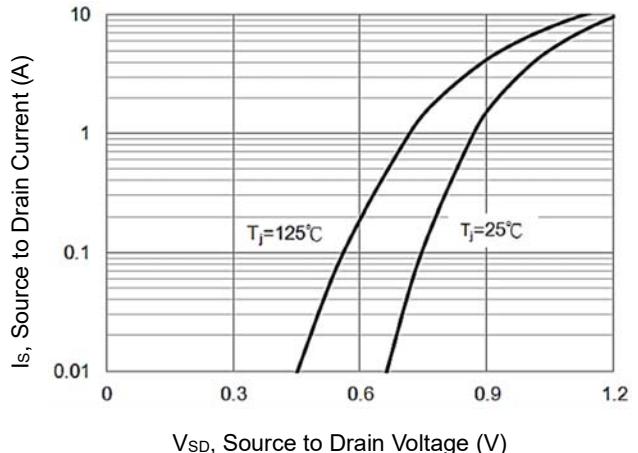
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P-CH CHARACTERISTIC CURVES

On-Resistance Variation with VGS



Body Diode



Capacitance vs. Drain-Source Voltage

